

# TK40F08K3-VB Datasheet N-Channel 100-V (D-S) MOSFET

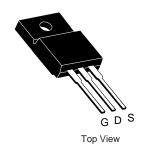
PRODUCT SUMMARY				
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)		
100	$0.0085 \text{ at V}_{GS} = 10 \text{ V}$	90		
100	0.0100 at V <sub>GS</sub> = 6 V	85		

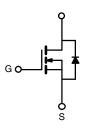
#### **FEATURES**

- TrenchFET® Power MOSFET
- 175 °C Maximum Junction Temperature
- Compliant to RoHS Directive 2002/95/EC









N-Channel MOSFET

ABSOLUTE MAXIMUM RATI	NGS T <sub>A</sub> = 25 °C, unless othe	rwise noted			
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	100	V	
Gate-Source Voltage		V <sub>GS</sub>	± 20	V	
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>C</sub> = 25 °C	I <sub>D</sub>	90		
	T <sub>C</sub> = 125 °C		70 <sup>a</sup>	А	
Pulsed Drain Current		I <sub>DM</sub>	287	A	
Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	75		
Single Pulse Avalanche Energy <sup>b</sup>	L = 0.1 IIII I	E <sub>AS</sub>	280	mJ	
Maximum Power Dissipation <sup>b</sup>	$T_C = 25  ^{\circ}C  (TO-220F)$	P <sub>D</sub>	56	W	
	T <sub>A</sub> = 25 °C (TO-220F)	ט י ט	3.75	]	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS				
Parameter		Symbol	Limit	Unit
Junction-to-Ambient	PCB Mount (TO-220) d	- R <sub>thJA</sub>	40	
Sunction-to-Ambient	Free Air (TO-220)	' 'thJA	62.5	°C/W
Junction-to-Case		R <sub>thJC</sub>	0.6	

#### Notes

- a. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static				•			
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V, } I_D = 250 \mu\text{A}$	100				
Gate-Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1		3	V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V			1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			50	μΑ	
		V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C			250		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} = \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	120			Α	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 30 A		0.0085			
	Ь	V <sub>GS</sub> = 6 V, I <sub>D</sub> = 20 A		0.0100		Ω	
Drain-Source On-State Resistance <sup>a</sup>	H <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 30 A, T <sub>J</sub> = 125 °C		0.0160			
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 30 A, T <sub>J</sub> = 175 °C		0.0210			
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	$V_{DS} = 15 \text{ V}, I_{D} = 30 \text{ A}$	25			S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			6550			
Output Capacitance	C <sub>oss</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 25 V, f = 1 MHz		665		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>	]		265			
Total Gate Charge <sup>c</sup>	$Q_g$			105			
Gate-Source Charge <sup>c</sup>	$Q_gs$	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 85 \text{ A}$		17		nC	
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$	7		23			
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			12	25		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 50 \text{ V}, R_{L} = 0.6 \Omega$		90	135		
Turn-Off DelayTime <sup>c</sup>	t <sub>d(off)</sub>	$I_D\cong 85~A,~V_{GEN}=10~V,~R_g=2.5~\Omega$		55	85	ns	
Fall Time <sup>c</sup>	t <sub>f</sub>	7		130	195	1	
Source-Drain Diode Ratings and Cha	racteristics T <sub>C</sub>	= 25 °C <sup>b</sup>					
Continuous Current	I <sub>S</sub>			90		^	
Pulsed Current	I <sub>SM</sub>			240		Α	
Forward Voltage <sup>a</sup>	$V_{SD}$	I <sub>F</sub> = 85 A, V <sub>GS</sub> = 0 V		1.0	1.5	V	
Reverse Recovery Time	t <sub>rr</sub>			85	140	ns	
Peak Reverse Recovery Current	I <sub>RM(REC)</sub>	I <sub>F</sub> = 50 A, dI/dt = 100 A/μs		4.5	7	Α	
Reverse Recovery Charge	Q <sub>rr</sub>	1		0.17	0.35	μC	

#### Notes:

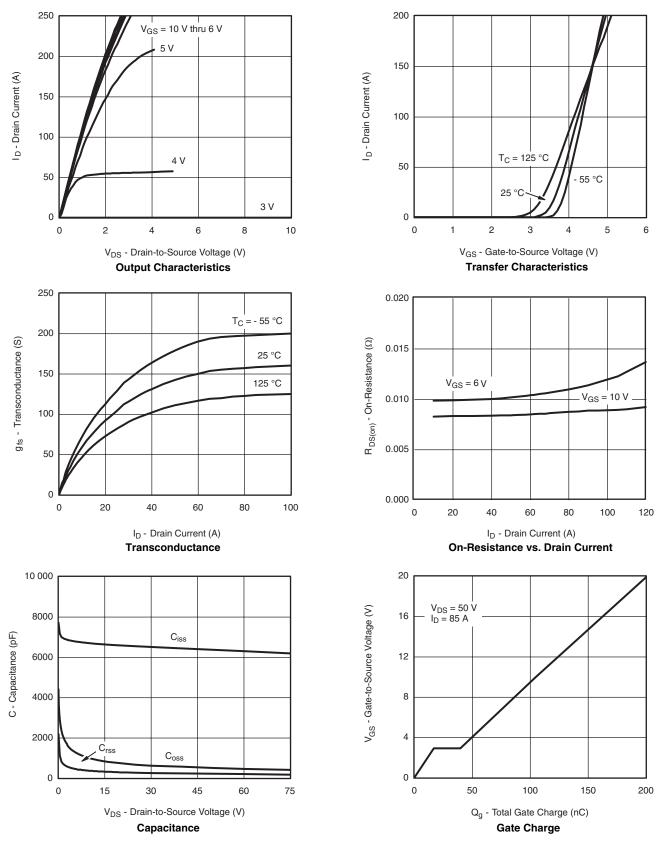
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- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



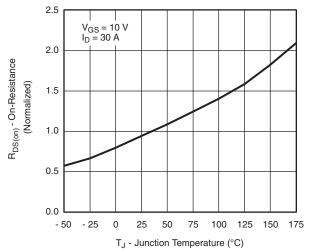
**TYPICAL CHARACTERISTICS**  $T_A = 25 \, ^{\circ}C$ , unless otherwise noted



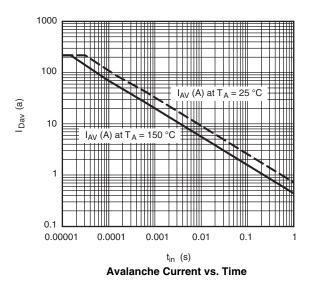
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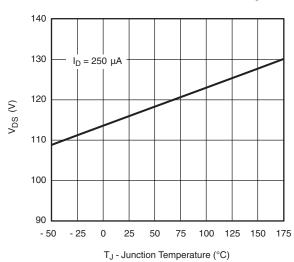
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#### On-Resistance vs. Junction Temperature



Source-Drain Diode Forward Voltage

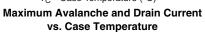


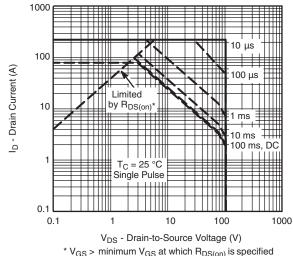
T<sub>J</sub> - Drain-Source Breakdown vs. Junction-Temperature



#### **THERMAL RATINGS**

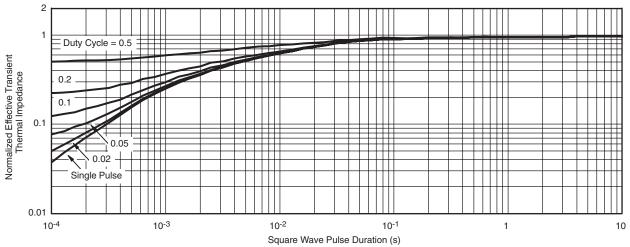






\*  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

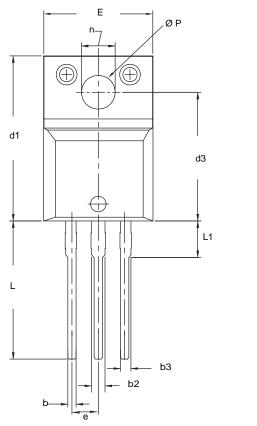


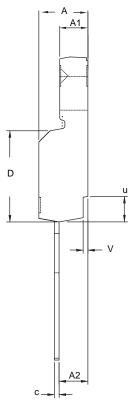


Normalized Thermal Transient Impedance, Junction-to-Case



### **TO-220 FULLPAK (HIGH VOLTAGE)**





DIM.	MILLII	METERS	INC	HES
	MIN.	MAX.	MIN.	MAX.
Α	4.570	4.830	0.180	0.190
A1	2.570	2.830	0.101	0.111
A2	2.510	2.850	0.099	0.112
b	0.622	0.890	0.024	0.035
b2	1.229	1.400	0.048	0.055
b3	1.229	1.400	0.048	0.055
С	0.440	0.629	0.017	0.025
D	8.650	9.800	0.341	0.386
d1	15.88	16.120	0.622	0.635
d3	12.300	12.920	0.484	0.509
E	10.360	10.630	0.408	0.419
е	2.54 BSC		0.100 BSC	
L	13.200	13.730	0.520	0.541
L1	3.100	3.500	0.122	0.138
n	6.050	6.150	0.238	0.242
Ø P	3.050	3.450	0.120	0.136
u	2.400	2.500	0.094	0.098
V	0.400	0.500	0.016	0.020

#### Notes

- To be used only for process drawing.
  These dimensions apply to all TO-220, FULLPAK leadframe versions 3 leads.
  All critical dimensions should C meet C<sub>pk</sub> > 1.33.
  All dimensions include burrs and plating thickness.
  No chipping or package damage.



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